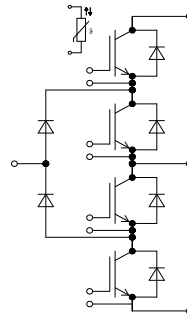
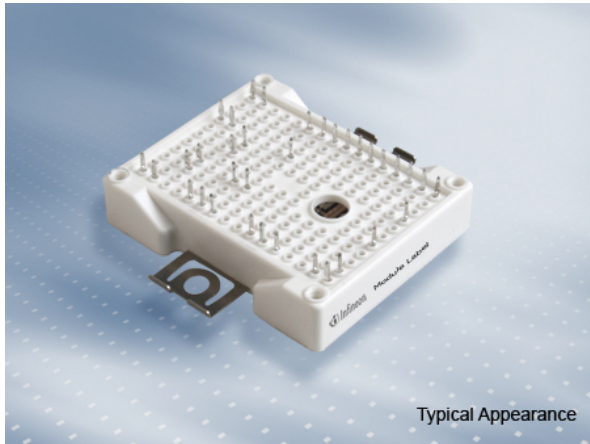


EasyPACK™ Modul mit TRENCHSTOP™ 5 und CoolSiC™ Schottky Diode und PressFIT / NTC
 EasyPACK™ module with TRENCHSTOP™ 5 and CoolSiC™ Schottky diode and PressFIT / NTC



$V_{CES} = 650V$

$I_{C\ nom} = 100A / I_{CRM} = 200A$

Potentielle Anwendungen

- 3-Level-Applikationen
- Motorantriebe
- Solar Anwendungen
- USV-Systeme

Elektrische Eigenschaften

- CoolSiC™ Schottky Diode Gen 5
- Erhöhte Sperrspannungsfestigkeit auf 650V
- Niedrige Schaltverluste

Mechanische Eigenschaften

- Al_2O_3 Substrat mit kleinem thermischen Widerstand
- Kompaktes Design
- PressFIT Verbindungstechnik
- Robuste Montage durch integrierte Befestigungsklammern

Potential Applications

- 3-level-applications
- Motor drives
- Solar applications
- UPS systems

Electrical Features

- CoolSiC™ Schottky diode gen 5
- Increased blocking voltage capability up to 650V
- Low switching losses

Mechanical Features

- Al_2O_3 substrate with low thermal resistance
- Compact design
- PressFIT contact technology
- Rugged mounting due to integrated mounting clamps

Module Label Code

Barcode Code 128



DMX - Code



Content of the Code

Content of the Code	Digit
Module Serial Number	1 - 5
Module Material Number	6 - 11
Production Order Number	12 - 19
Datecode (Production Year)	20 - 21
Datecode (Production Week)	22 - 23

IGBT, T1 / T4 / IGBT, T1 / T4**Höchstzulässige Werte / Maximum Rated Values**

Kollektor-Emitter-Sperrspannung Collector-emitter voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{CES}	650	V
Implementierter Kollektor-Strom Implemented collector current		I_{CN}	200	A
Kollektor-Dauergleichstrom Continuous DC collector current	$T_H = 65^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$	I_{CDC}	95	A
Periodischer Kollektor-Spitzenstrom Repetitive peak collector current	$t_P = 1\text{ ms}$	I_{CRM}	400	A
Gate-Emitter-Spitzenspannung Gate-emitter peak voltage		V_{GES}	+/-20	V

Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage	$I_C = 100\text{ A}$ $V_{GE} = 15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{CE\text{ sat}}$	1,17 1,20 1,21	1,38	V V V
Gate-Schwellenspannung Gate threshold voltage	$I_C = 2,00\text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$		$V_{G\text{Eth}}$	3,25	4,00	4,75 V
Gateladung Gate charge	$V_{GE} = -15 / 15\text{ V}, V_{CE} = 400\text{ V}$		Q_G	0,84		μC
Interner Gatewiderstand Internal gate resistor	$T_{vj} = 25^{\circ}\text{C}$		$R_{G\text{int}}$	0,0		Ω
Eingangskapazität Input capacitance	$f = 100\text{ kHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{ies}	14,3		nF
Rückwirkungskapazität Reverse transfer capacitance	$f = 100\text{ kHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{res}	0,05		nF
Kollektor-Emitter-Reststrom Collector-emitter cut-off current	$V_{CE} = 650\text{ V}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$	I_{CES}		1,0	mA
Gate-Emitter-Reststrom Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$		I_{GES}		100	nA
Einschaltverzögerungszeit, induktive Last Turn-on delay time, inductive load	$I_C = 100\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{Gon} = 20\text{ }\Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{d\text{ on}}$	0,097 0,087 0,082		μs μs μs
Anstiegszeit, induktive Last Rise time, inductive load	$I_C = 100\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{Gon} = 20\text{ }\Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_r	0,046 0,05 0,054		μs μs μs
Abschaltverzögerungszeit, induktive Last Turn-off delay time, inductive load	$I_C = 100\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{Goff} = 39\text{ }\Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{d\text{ off}}$	0,654 0,687 0,704		μs μs μs
Fallzeit, induktive Last Fall time, inductive load	$I_C = 100\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{Goff} = 39\text{ }\Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_f	0,029 0,033 0,033		μs μs μs
Einschaltverlustenergie pro Puls Turn-on energy loss per pulse	$I_C = 100\text{ A}, V_{CE} = 300\text{ V}, L\sigma = 35\text{ nH}$ $di/dt = 1800\text{ A}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $V_{GE} = -15 / 15\text{ V}, R_{Gon} = 20\text{ }\Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{on}	2,79 3,20 3,51		mJ mJ mJ
Abschaltverlustenergie pro Puls Turn-off energy loss per pulse	$I_C = 100\text{ A}, V_{CE} = 300\text{ V}, L\sigma = 35\text{ nH}$ $du/dt = 3700\text{ V}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $V_{GE} = -15 / 15\text{ V}, R_{Goff} = 39\text{ }\Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{off}	1,21 1,48 1,61		mJ mJ mJ
Kurzschlußverhalten SC data	$V_{GE} \leq 15\text{ V}, V_{CC} = 360\text{ V}$ $V_{CE\text{ max}} = V_{CES} - L_{sCE} \cdot di/dt$	$t_P \leq 0\text{ }\mu\text{s}, T_{vj} = 150^{\circ}\text{C}$	I_{SC}	1600		A
Wärmewiderstand, Chip bis Kühlkörper Thermal resistance, junction to heatsink	pro IGBT / per IGBT		R_{thJH}	0,814		K/W
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\text{ op}}$	-40	150	$^{\circ}\text{C}$

IGBT, T2 / T3 / IGBT, T2 / T3**Höchstzulässige Werte / Maximum Rated Values**

Kollektor-Emitter-Sperrspannung Collector-emitter voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{CES}	650	V
Implementierter Kollektor-Strom Implemented collector current		I_{CN}	200	A
Kollektor-Dauergleichstrom Continuous DC collector current	$T_H = 65^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$	I_{CDC}	95	A
Periodischer Kollektor-Spitzenstrom Repetitive peak collector current	$t_P = 1\text{ ms}$	I_{CRM}	400	A
Gate-Emitter-Spitzenspannung Gate-emitter peak voltage		V_{GES}	+/-20	V

Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage	$I_C = 100\text{ A}$ $V_{GE} = 15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{CE\text{ sat}}$	1,17 1,20 1,21	1,38	V V V
Gate-Schwellenspannung Gate threshold voltage	$I_C = 2,00\text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$		$V_{G\text{Eth}}$	3,25	4,00	4,75 V
Gateladung Gate charge	$V_{GE} = -15 / 15\text{ V}, V_{CE} = 400\text{ V}$		Q_G	0,84		μC
Interner Gatewiderstand Internal gate resistor	$T_{vj} = 25^{\circ}\text{C}$		$R_{G\text{int}}$	0,0		Ω
Eingangskapazität Input capacitance	$f = 100\text{ kHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{ies}	14,3		nF
Rückwirkungskapazität Reverse transfer capacitance	$f = 100\text{ kHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{res}	0,05		nF
Kollektor-Emitter-Reststrom Collector-emitter cut-off current	$V_{CE} = 650\text{ V}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$	I_{CES}		0,044	mA
Gate-Emitter-Reststrom Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$		I_{GES}		100	nA
Einschaltverzögerungszeit, induktive Last Turn-on delay time, inductive load	$I_C = 100\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{G\text{on}} = 20\text{ }\Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{d\text{ on}}$	0,098 0,087 0,085		μs μs μs
Anstiegszeit, induktive Last Rise time, inductive load	$I_C = 100\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{G\text{on}} = 20\text{ }\Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_r	0,037 0,043 0,046		μs μs μs
Abschaltverzögerungszeit, induktive Last Turn-off delay time, inductive load	$I_C = 100\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{G\text{off}} = 39\text{ }\Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{d\text{ off}}$	0,651 0,685 0,695		μs μs μs
Fallzeit, induktive Last Fall time, inductive load	$I_C = 100\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{G\text{off}} = 39\text{ }\Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_f	0,018 0,024 0,026		μs μs μs
Einschaltverlustenergie pro Puls Turn-on energy loss per pulse	$I_C = 100\text{ A}, V_{CE} = 300\text{ V}, L\sigma = 35\text{ nH}$ $di/dt = 2200\text{ A}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $V_{GE} = -15 / 15\text{ V}, R_{G\text{on}} = 20\text{ }\Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{on}	2,18 2,56 2,79		mJ mJ mJ
Abschaltverlustenergie pro Puls Turn-off energy loss per pulse	$I_C = 100\text{ A}, V_{CE} = 300\text{ V}, L\sigma = 35\text{ nH}$ $du/dt = 3500\text{ V}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $V_{GE} = -15 / 15\text{ V}, R_{G\text{off}} = 39\text{ }\Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{off}	1,28 1,65 1,80		mJ mJ mJ
Kurzschlußverhalten SC data	$V_{GE} \leq 15\text{ V}, V_{CC} = 360\text{ V}$ $V_{CE\text{ max}} = V_{CES} - L_{\text{SCE}} \cdot di/dt$	$t_P \leq 0\text{ }\mu\text{s}, T_{vj} = 150^{\circ}\text{C}$	I_{SC}	1600		A
Wärmewiderstand, Chip bis Kühlkörper Thermal resistance, junction to heatsink	pro IGBT / per IGBT		$R_{th\text{JH}}$	0,814		K/W
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\text{ op}}$	-40	150	$^{\circ}\text{C}$

Diode, D1 / D4 / Diode, D1 / D4**Höchstzulässige Werte / Maximum Rated Values**

Periodische Spitzenspannung Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{RRM}	650	V
Implementierter Durchlassstrom Implemented forward current		I_{FN}	120	A
Dauergleichstrom Continuous DC forward current		I_F	100	A
Periodischer Spitzenstrom Repetitive peak forward current	$t_P = 1\text{ ms}$	I_{FRM}	240	A
Grenzlastintegral I^2t - value	$V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 150^{\circ}\text{C}$	I^2t	700 690	A^2s A^2s

Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Durchlassspannung Forward voltage	$I_F = 100\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 100\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 100\text{ A}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	V_F	1,38 1,49 1,52	1,65	V V V
Rückstromspitze Peak reverse recovery current	$I_F = 100\text{ A}, -di_F/dt = 1800\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	I_{RM}	58,3 74,4 77,6		A A A
Sperrverzögerungsladung Recovered charge	$I_F = 100\text{ A}, -di_F/dt = 1800\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	Q_r	3,10 5,40 5,50		μC μC μC
Abschaltenergie pro Puls Reverse recovery energy	$I_F = 100\text{ A}, -di_F/dt = 1800\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{rec}	0,50 0,57 0,69		mJ mJ mJ
Wärmewiderstand, Chip bis Kühlkörper Thermal resistance, junction to heatsink	pro Diode / per diode		R_{thJH}	1,15		K/W
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\text{ op}}$	-40	150	$^{\circ}\text{C}$

Diode, D2 / D3 / Diode, D2 / D3**Höchstzulässige Werte / Maximum Rated Values**

Periodische Spitzenspannung Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{RRM}	650	V
Implementierter Durchlassstrom Implemented forward current		I_{FN}	150	A
Dauergleichstrom Continuous DC forward current		I_F	100	A
Periodischer Spitzenstrom Repetitive peak forward current	$t_P = 1\text{ ms}$	I_{FRM}	300	A
Grenzlastintegral I^2t - value	$V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 150^{\circ}\text{C}$	I^2t	770 690	A^2s A^2s

Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Durchlassspannung Forward voltage	$I_F = 100\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 100\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 100\text{ A}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	V_F	1,33 1,29 1,26	1,55	V V V
Rückstromspitze Peak reverse recovery current	$I_F = 100\text{ A}, -di_F/dt = 2200\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	I_{RM}	47,6 49,8 52,7		A A A
Sperrverzögerungsladung Recovered charge	$I_F = 100\text{ A}, -di_F/dt = 2200\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	Q_r	1,90 2,00 2,10		μC μC μC
Abschaltenergie pro Puls Reverse recovery energy	$I_F = 100\text{ A}, -di_F/dt = 2200\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{rec}	0,527 0,965 1,11		mJ mJ mJ
Wärmewiderstand, Chip bis Kühlkörper Thermal resistance, junction to heatsink	pro Diode / per diode		R_{thJH}	0,953		K/W
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\text{ op}}$	-40	150	$^{\circ}\text{C}$

Diode, D5-D6 / Diode, D5-D6**Höchstzulässige Werte / Maximum Rated Values**

Periodische Spitzensperrspannung Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{RRM}	650	V
Implementierter Durchlassstrom Implemented forward current		I_{FN}	120	A
Dauergleichstrom Continuous DC forward current		I_F	100	A
Periodischer Spitzenstrom Repetitive peak forward current	$t_P = 1\text{ ms}$	I_{FRM}	240	A
Grenzlastintegral I^2t - value	$V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 150^{\circ}\text{C}$	I^2t	700 690	A^2s A^2s

Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Durchlassspannung Forward voltage	$I_F = 100\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 100\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 100\text{ A}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	V_F	1,38 1,49 1,52	1,65	V V V
Rückstromspitze Peak reverse recovery current	$I_F = 100\text{ A}, -di_F/dt = 1800\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	I_{RM}	58,3 74,4 77,6		A A A
Sperrverzögerungsladung Recovered charge	$I_F = 100\text{ A}, -di_F/dt = 1800\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	Q_r	3,10 5,40 5,50		μC μC μC
Abschaltenergie pro Puls Reverse recovery energy	$I_F = 100\text{ A}, -di_F/dt = 1800\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{rec}	0,50 0,57 0,69		mJ mJ mJ
Wärmewiderstand, Chip bis Kühlkörper Thermal resistance, junction to heatsink	pro Diode / per diode		R_{thJH}	1,15		K/W
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\text{ op}}$	-40	150	$^{\circ}\text{C}$

NTC-Widerstand / NTC-Thermistor**Charakteristische Werte / Characteristic Values**

			min.	typ.	max.	
Nennwiderstand Rated resistance	$T_{NTC} = 25^{\circ}\text{C}$	R_{25}		5,00		k Ω
Abweichung von R100 Deviation of R100	$T_{NTC} = 100^{\circ}\text{C}, R_{100} = 493\text{ }\Omega$	$\Delta R/R$	-5		5	%
Verlustleistung Power dissipation	$T_{NTC} = 25^{\circ}\text{C}$	P_{25}			20,0	mW
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15\text{ K}))]$	$B_{25/50}$		3375		K
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15\text{ K}))]$	$B_{25/80}$		3411		K
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15\text{ K}))]$	$B_{25/100}$		3433		K

Angaben gemäß gültiger Application Note.

Specification according to the valid application note.

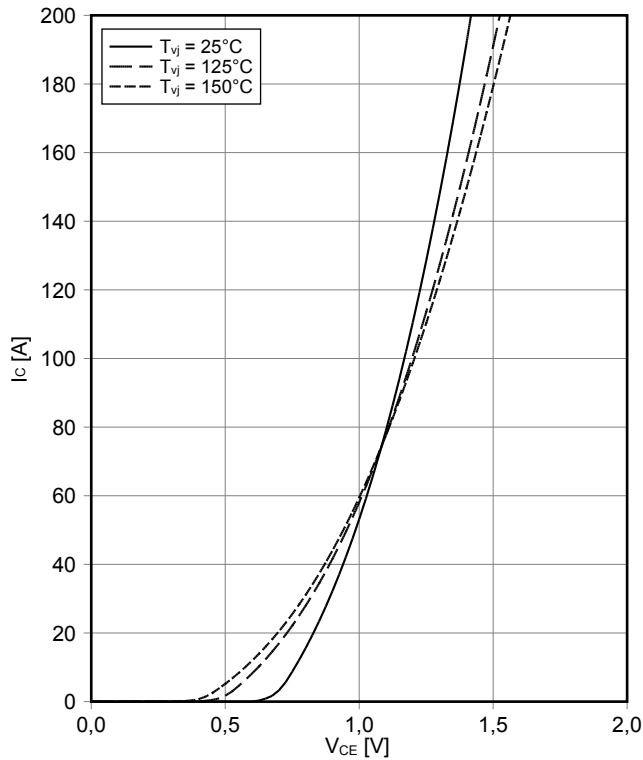
Modul / Module

Isolations-Prüfspannung Isolation test voltage	RMS, f = 50 Hz, t = 1 min.	V _{ISOL}	2,5	kV	
Innere Isolation Internal isolation	Basisisolierung (Schutzklasse 1, EN61140) basic insulation (class 1, IEC 61140)		Al ₂ O ₃		
Kriechstrecke Creepage distance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		11,5 6,3	mm	
Luftstrecke Clearance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		10,0 5,0	mm	
Vergleichszahl der Kriechwegbildung Comperative tracking index		CTI	> 200		
Relativer Temperaturindex (elektr.) RTI Elec.	Gehäuse housing	RTI	140	°C	
			min.	typ.	max.
Modulstreuinduktivität Stray inductance module		L _{sCE}		20	nH
Lagertemperatur Storage temperature		T _{stg}	-40		125 °C
Anpresskraft für mech. Bef. pro Feder mounting force per clamp		F	40	-	80 N
Gewicht Weight		G		39	g

Der Strom im Dauerbetrieb ist auf 25A effektiv pro Anschlusspin begrenzt.
The current under continuous operation is limited to 25A rms per connector pin.

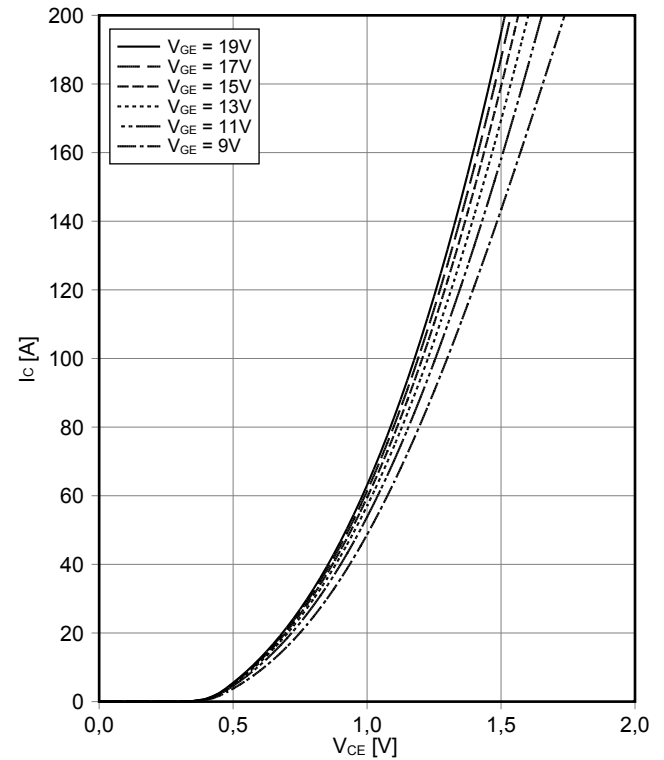
Ausgangskennlinie IGBT, T1 / T4 (typisch)
output characteristic IGBT, T1 / T4 (typical)

$I_C = f(V_{CE})$
 $V_{GE} = 15 \text{ V}$



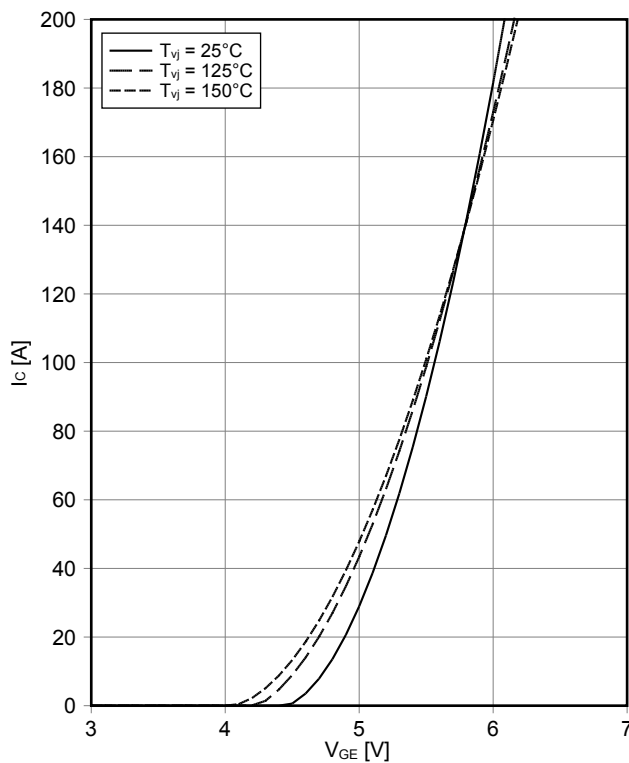
Ausgangskennlinienfeld IGBT, T1 / T4 (typisch)
output characteristic IGBT, T1 / T4 (typical)

$I_C = f(V_{CE})$
 $T_{vj} = 150^\circ\text{C}$



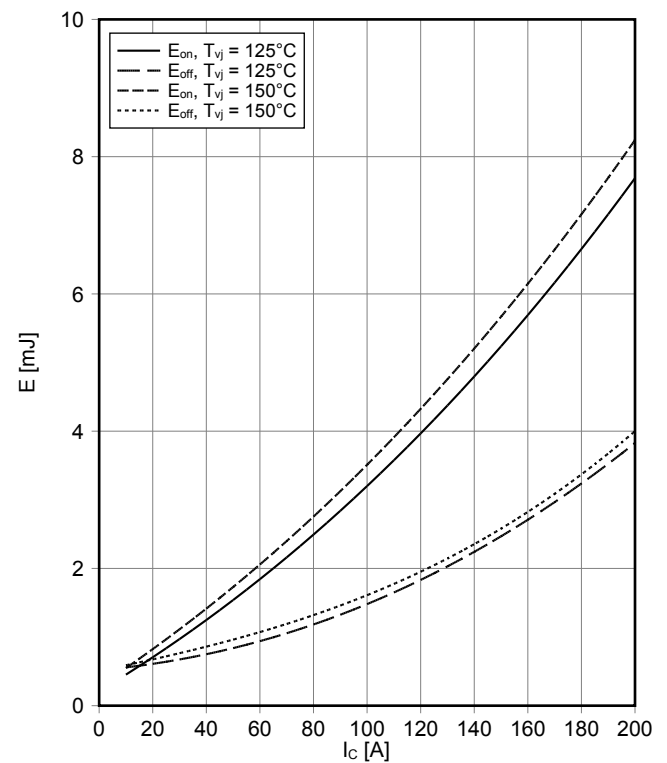
Übertragungscharakteristik IGBT, T1 / T4 (typisch)
transfer characteristic IGBT, T1 / T4 (typical)

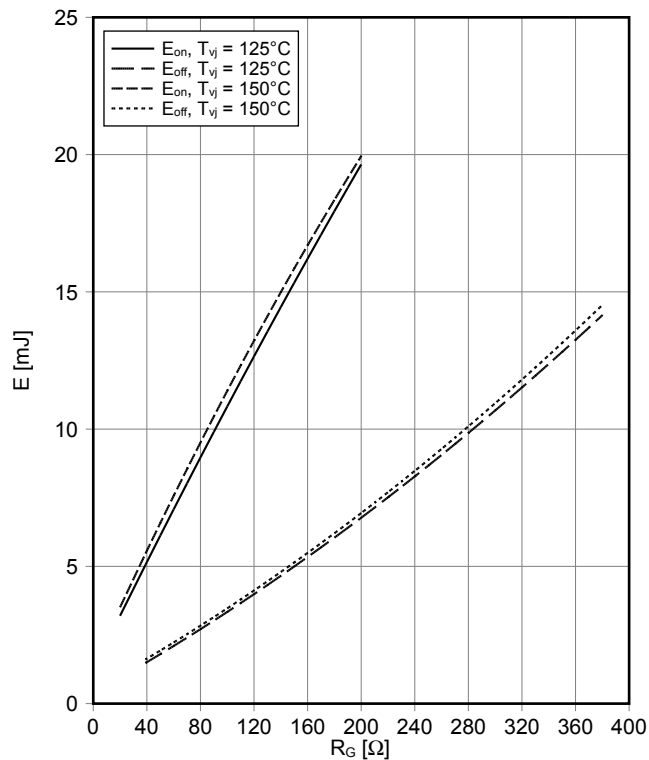
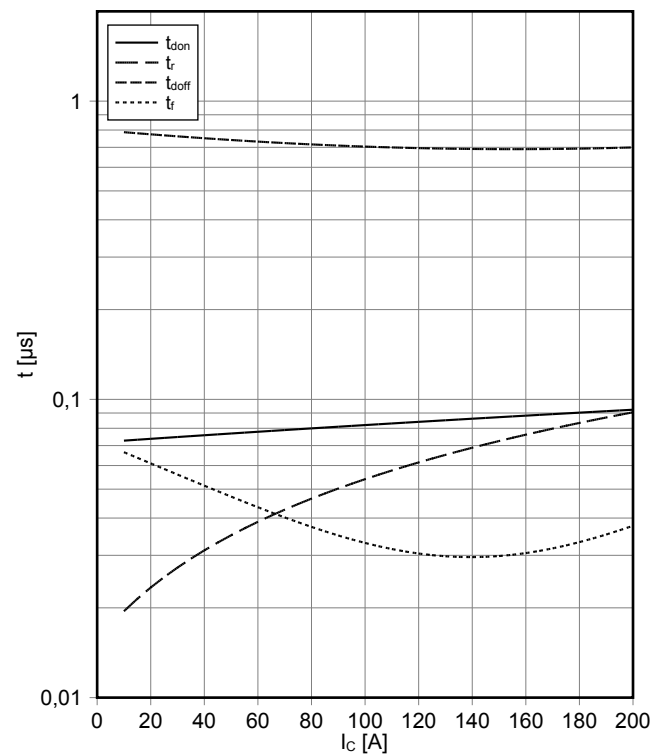
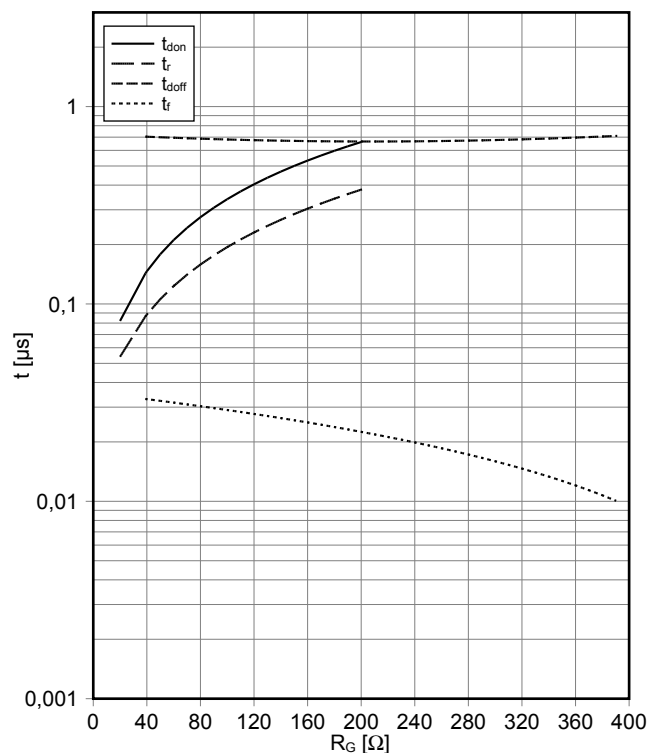
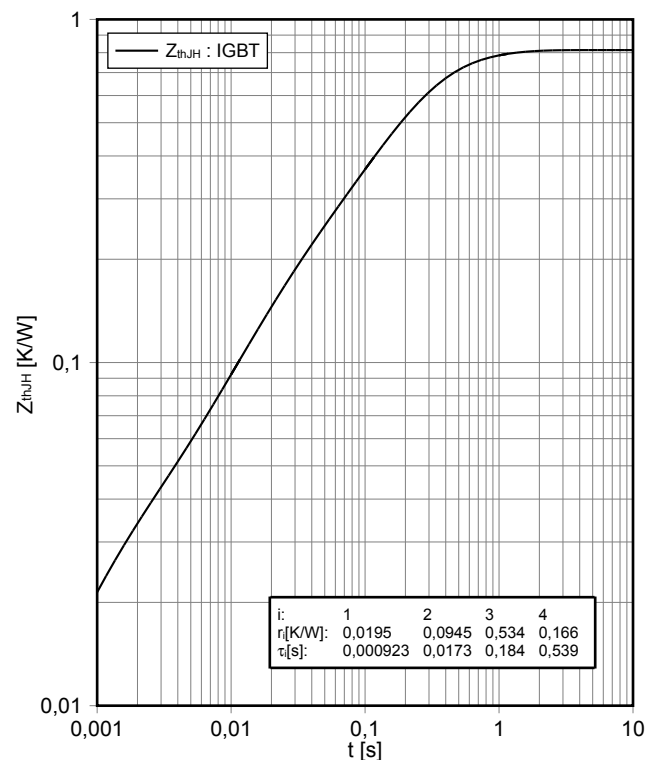
$I_C = f(V_{GE})$
 $V_{CE} = 20 \text{ V}$



Schaltverluste IGBT, T1 / T4 (typisch)
switching losses IGBT, T1 / T4 (typical)

$E_{on} = f(I_C)$, $E_{off} = f(I_C)$
 $V_{GE} = \pm 15 \text{ V}$, $R_{Gon} = 20 \Omega$, $R_{Goff} = 39 \Omega$, $V_{CE} = 300 \text{ V}$

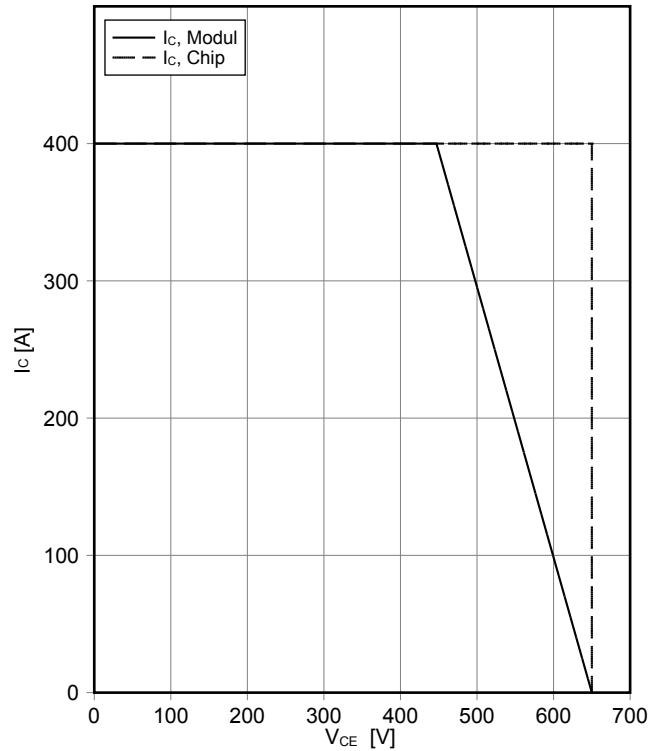


Schaltverluste IGBT, T1 / T4 (typisch)
switching losses IGBT, T1 / T4 (typical)
 $E_{on} = f(R_G), E_{off} = f(R_G)$
 $V_{GE} = \pm 15 \text{ V}, I_C = 100 \text{ A}, V_{CE} = 300 \text{ V}$

Schaltzeiten IGBT, T1 / T4 (typisch)
switching times IGBT, T1 / T4 (typical)
 $t_{don} = f(I_C), t_r = f(I_C), t_{doff} = f(I_C), t_f = f(I_C)$
 $V_{GE} = \pm 15 \text{ V}, R_{Gon} = 20 \Omega, R_{Goff} = 39 \Omega, V_{CE} = 300 \text{ V}, T_{vj} = 150^\circ\text{C}$

Schaltzeiten IGBT, T1 / T4 (typisch)
switching times IGBT, T1 / T4 (typical)
 $t_{don} = f(R_G), t_r = f(R_G), t_{doff} = f(R_G), t_f = f(R_G)$
 $V_{GE} = \pm 15 \text{ V}, I_C = 100 \text{ A}, V_{CE} = 300 \text{ V}, T_{vj} = 150^\circ\text{C}$

Transienter Wärmewiderstand IGBT, T1 / T4
transient thermal impedance IGBT, T1 / T4
 $Z_{thJH} = f(t)$


Sicherer Rückwärts-Arbeitsbereich IGBT, T1 / T4 (RBSOA) reverse bias safe operating area IGBT, T1 / T4 (RBSOA)

$I_C = f(V_{CE})$

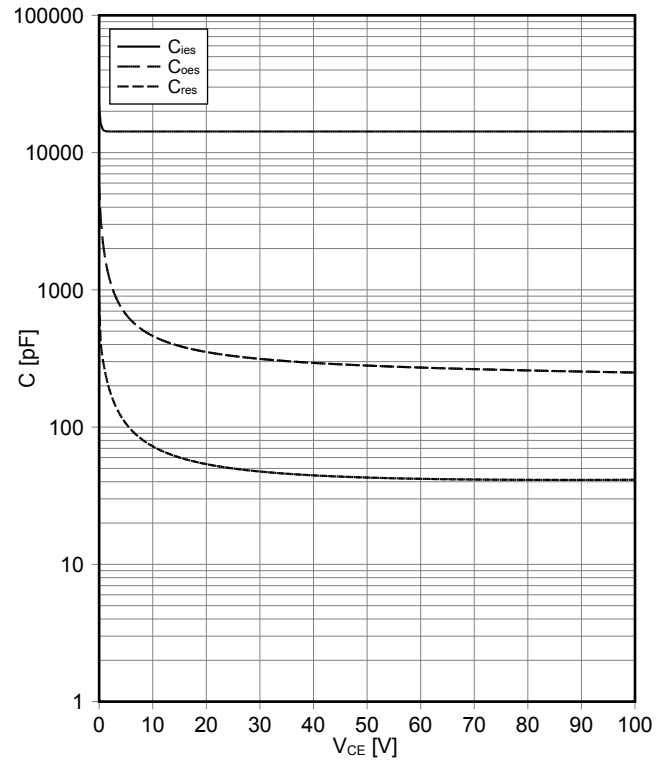
$V_{GE} = \pm 15 \text{ V}$, $R_{Goff} = 39 \Omega$, $T_{vj} = 150^\circ\text{C}$



Kapazitäts Charakteristik IGBT, T1 / T4 (typisch) capacity characteristic IGBT, T1 / T4 (typical)

$C = f(V_{CE})$

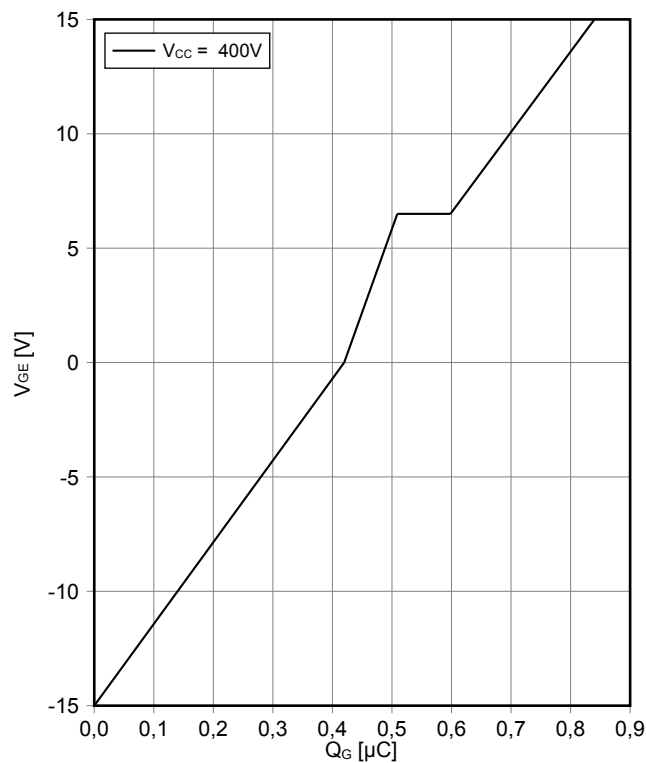
$V_{GE} = 0 \text{ V}$, $T_{vj} = 25^\circ\text{C}$, $f = 100\text{kHz}$



Gateladungs Charakteristik IGBT, T1 / T4 (typisch) gate charge characteristic IGBT, T1 / T4 (typical)

$V_{GE} = f(Q_G)$

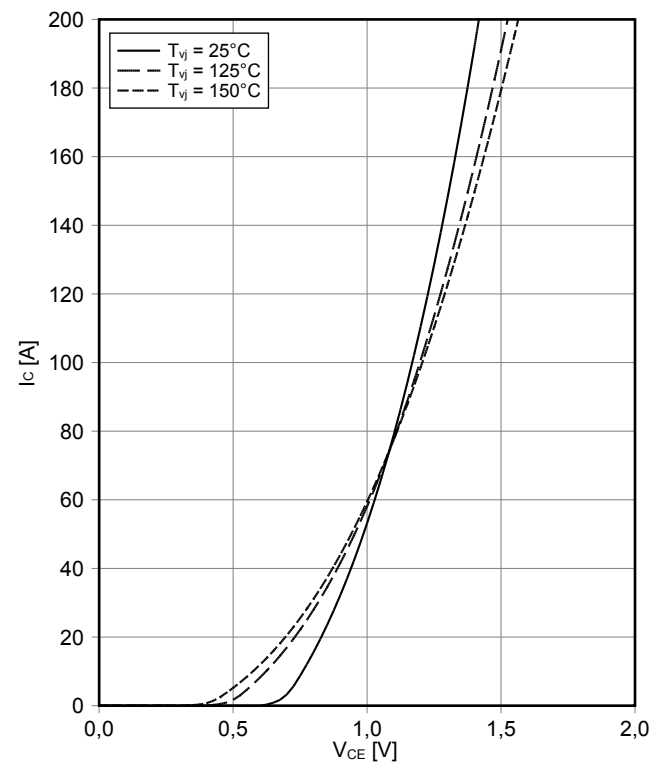
$I_C = 200 \text{ A}$, $T_{vj} = 25^\circ\text{C}$



Ausgangskennlinie IGBT, T2 / T3 (typisch) output characteristic IGBT, T2 / T3 (typical)

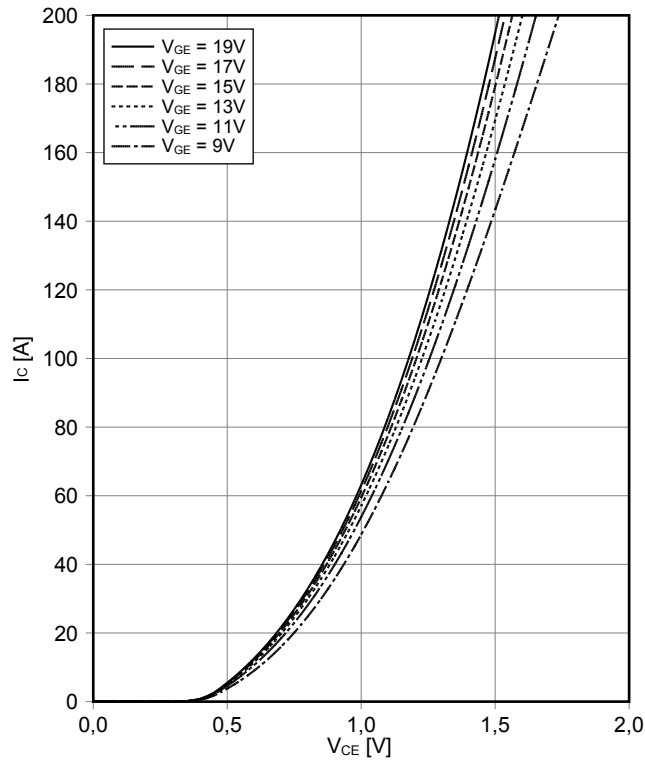
$I_C = f(V_{CE})$

$V_{GE} = 15 \text{ V}$



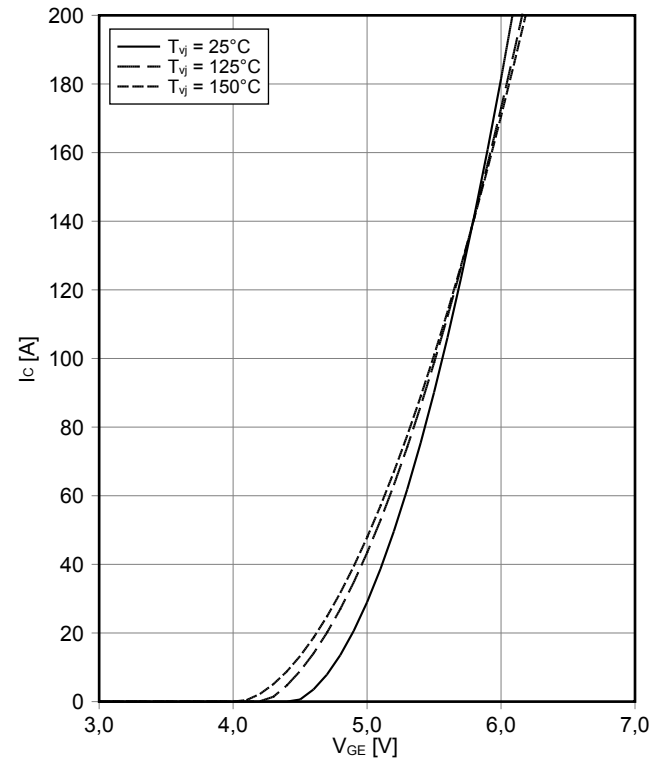
Ausgangskennlinienfeld IGBT, T2 / T3 (typisch)
output characteristic IGBT, T2 / T3 (typical)

$I_C = f(V_{CE})$
 $T_{vj} = 150^\circ\text{C}$



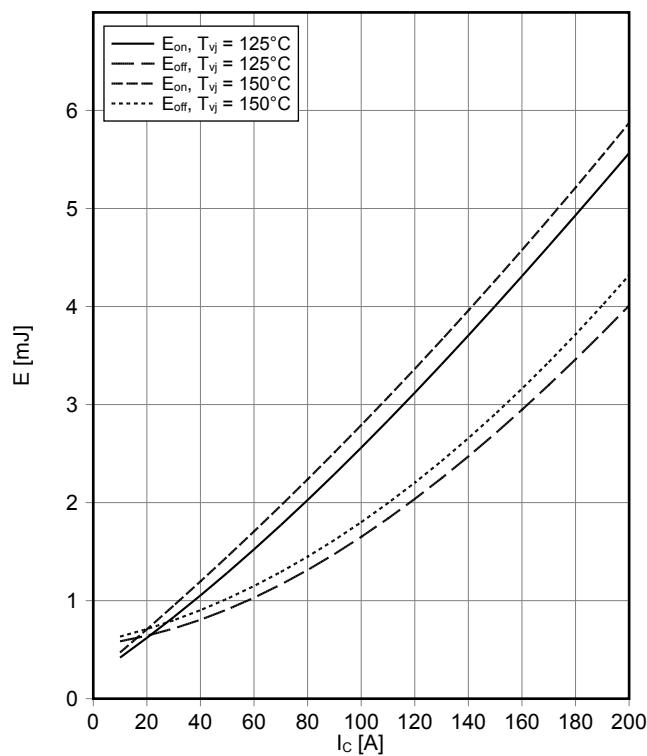
Übertragungscharakteristik IGBT, T2 / T3 (typisch)
transfer characteristic IGBT, T2 / T3 (typical)

$I_C = f(V_{GE})$
 $V_{CE} = 20\text{ V}$



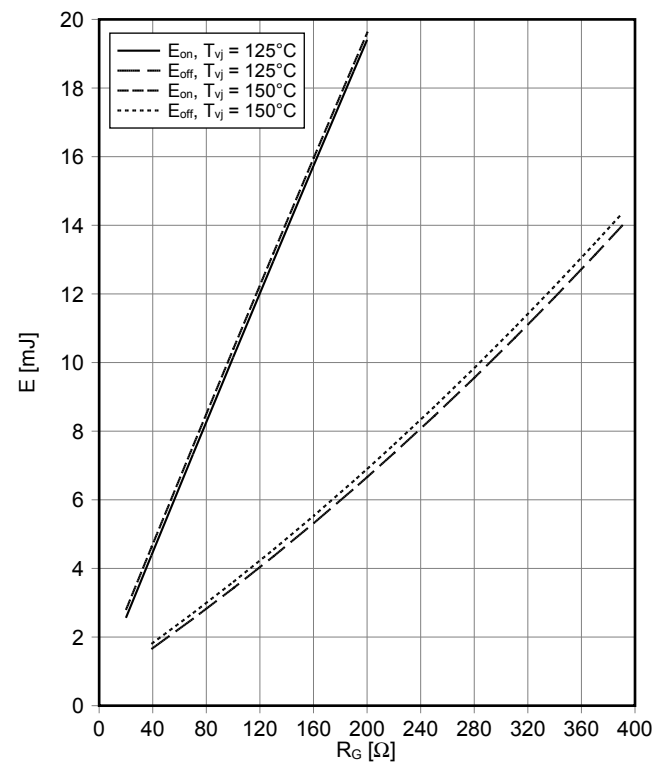
Schaltverluste IGBT, T2 / T3 (typisch)
switching losses IGBT, T2 / T3 (typical)

$E_{on} = f(I_C)$, $E_{off} = f(I_C)$
 $V_{GE} = \pm 15\text{ V}$, $R_{Gon} = 20\ \Omega$, $R_{Goff} = 39\ \Omega$, $V_{CE} = 300\text{ V}$



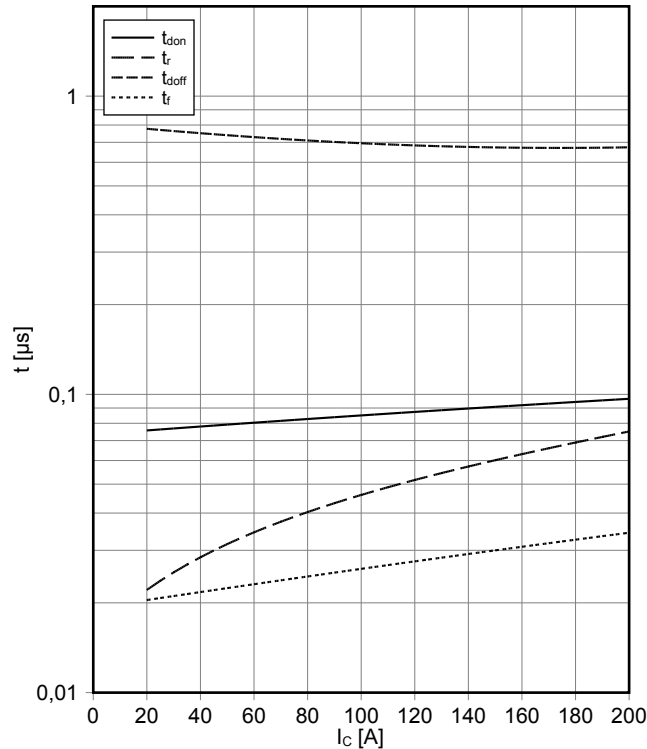
Schaltverluste IGBT, T2 / T3 (typisch)
switching losses IGBT, T2 / T3 (typical)

$E_{on} = f(R_G)$, $E_{off} = f(R_G)$
 $V_{GE} = \pm 15\text{ V}$, $I_C = 100\text{ A}$, $V_{CE} = 300\text{ V}$



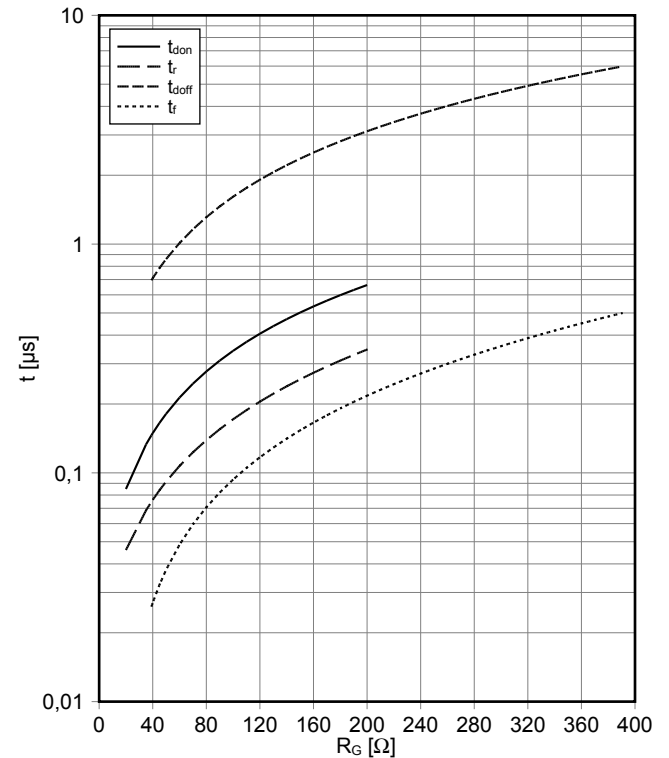
Schaltzeiten IGBT, T2 / T3 (typisch) switching times IGBT, T2 / T3 (typical)

$t_{don} = f(I_C)$, $t_r = f(I_C)$, $t_{doff} = f(I_C)$, $t_f = f(I_C)$
 $V_{GE} = \pm 15 \text{ V}$, $R_{Gon} = 20 \Omega$, $R_{Goff} = 39 \Omega$, $V_{CE} = 300 \text{ V}$, $T_{vj} = 150^\circ\text{C}$



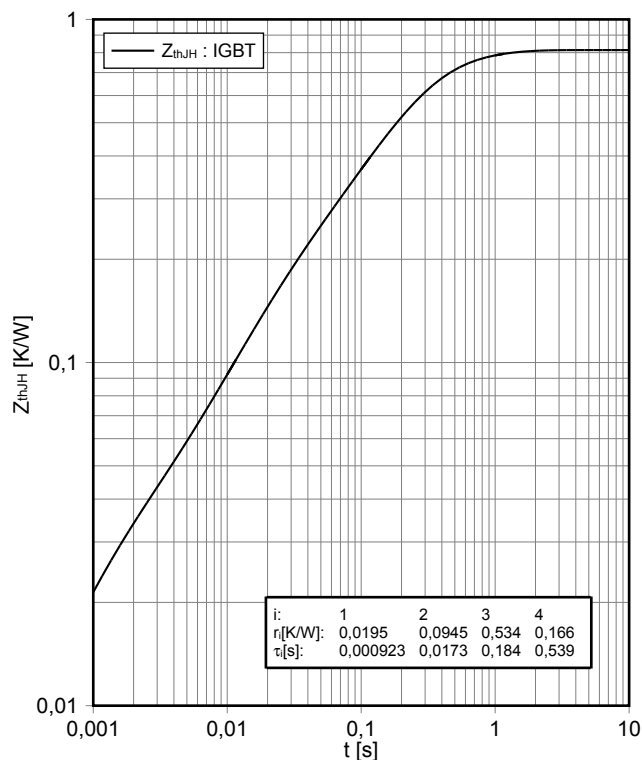
Schaltzeiten IGBT, T2 / T3 (typisch) switching times IGBT, T2 / T3 (typical)

$t_{don} = f(R_G)$, $t_r = f(R_G)$, $t_{doff} = f(R_G)$, $t_f = f(R_G)$
 $V_{GE} = \pm 15 \text{ V}$, $I_C = 100 \text{ A}$, $V_{CE} = 300 \text{ V}$, $T_{vj} = 150^\circ\text{C}$



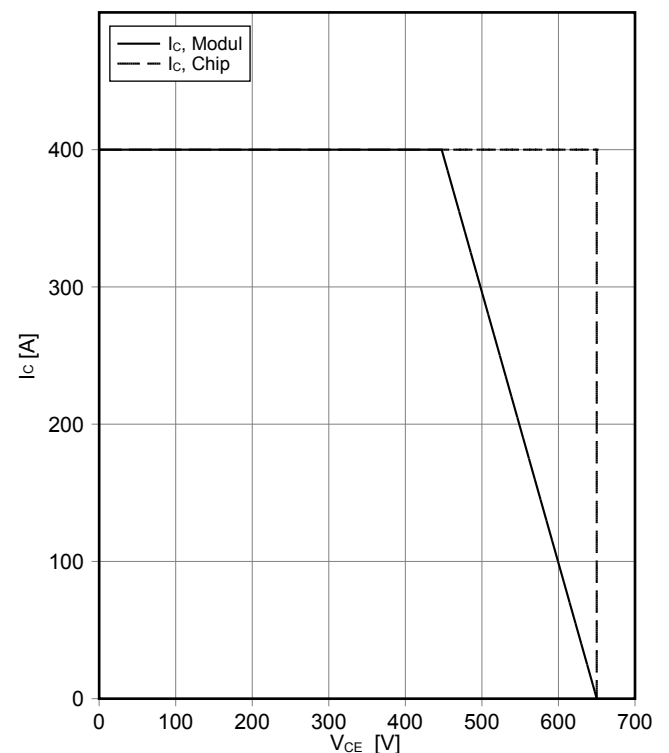
Transienter Wärmewiderstand IGBT, T2 / T3 transient thermal impedance IGBT, T2 / T3

$Z_{thJH} = f(t)$



Sicherer Rückwärts-Arbeitsbereich IGBT, T2 / T3 (RBSOA) reverse bias safe operating area IGBT, T2 / T3 (RBSOA)

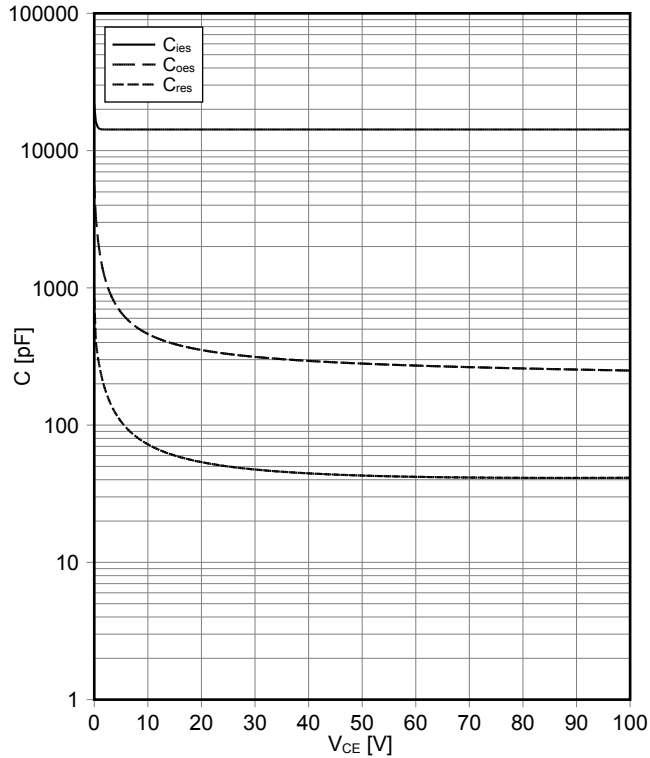
$I_C = f(V_{CE})$
 $V_{GE} = \pm 15 \text{ V}$, $R_{Goff} = 39 \Omega$, $T_{vj} = 150^\circ\text{C}$



Kapazitäts Charakteristik IGBT, T2 / T3 (typisch) capacity characteristic IGBT, T2 / T3 (typical)

$$C = f(V_{CE})$$

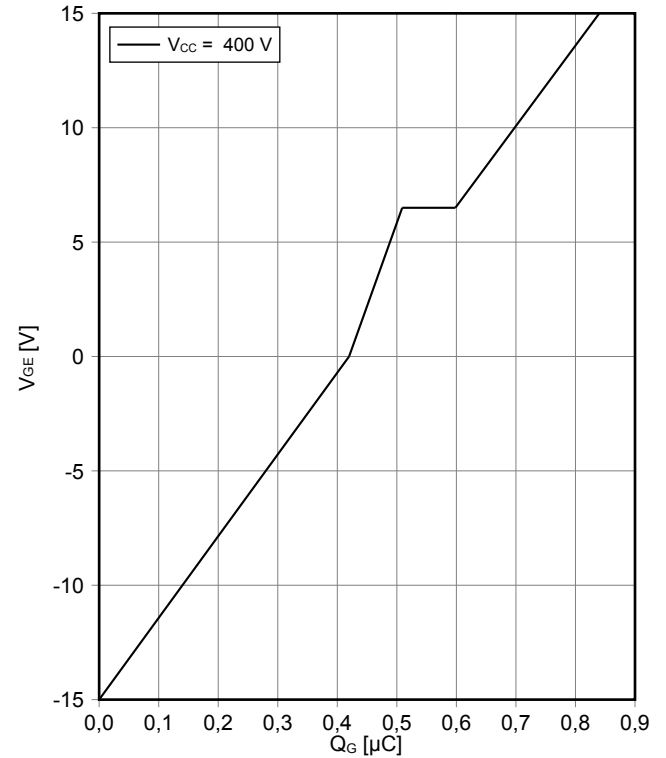
$V_{GE} = 0 \text{ V}$, $T_{vj} = 25^\circ\text{C}$, $f = 100\text{kHz}$



Gateladungs Charakteristik IGBT, T2 / T3 (typisch) gate charge characteristic IGBT, T2 / T3 (typical)

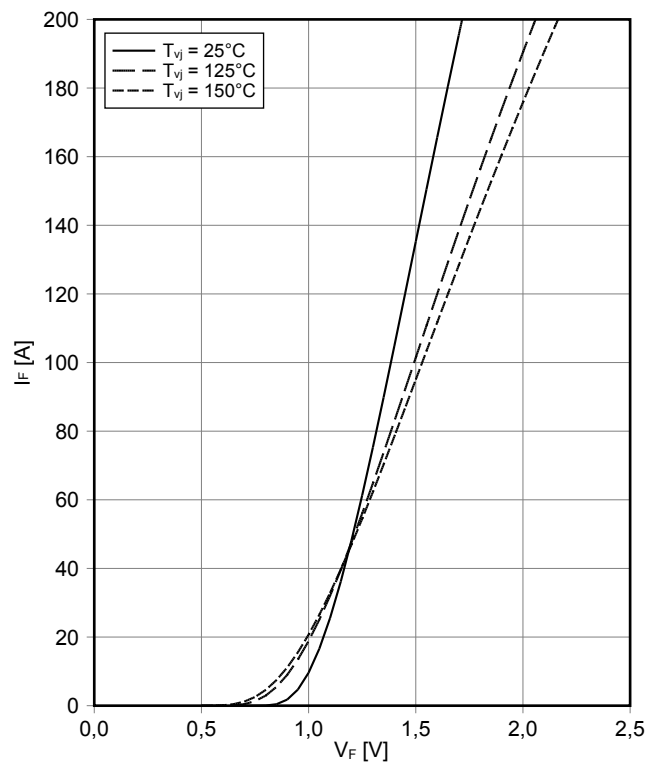
$$V_{GE} = f(Q_G)$$

$I_C = 200 \text{ A}$, $T_{vj} = 25^\circ\text{C}$



Durchlasskennlinie der Diode, D1 / D4 (typisch) forward characteristic of Diode, D1 / D4 (typical)

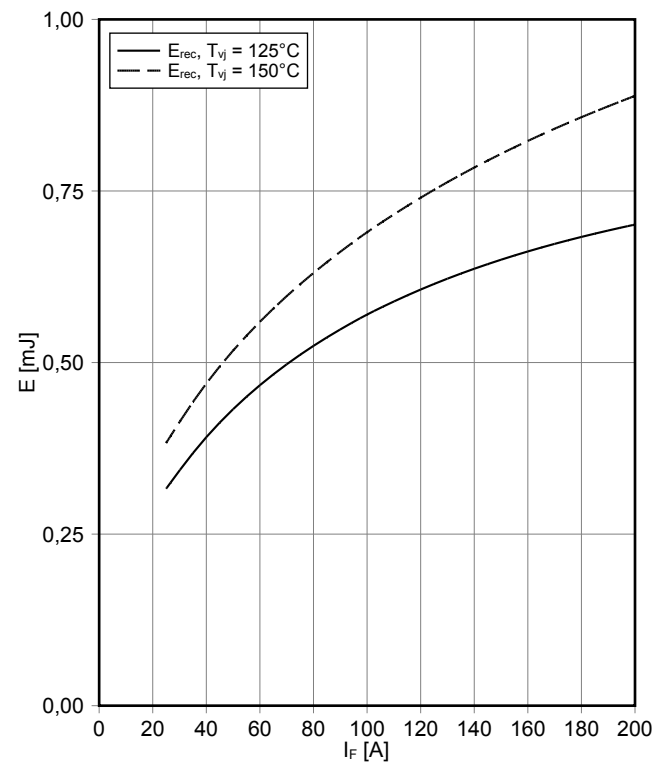
$$I_F = f(V_F)$$



Schaltverluste Diode, D1 / D4 (typisch) switching losses Diode, D1 / D4 (typical)

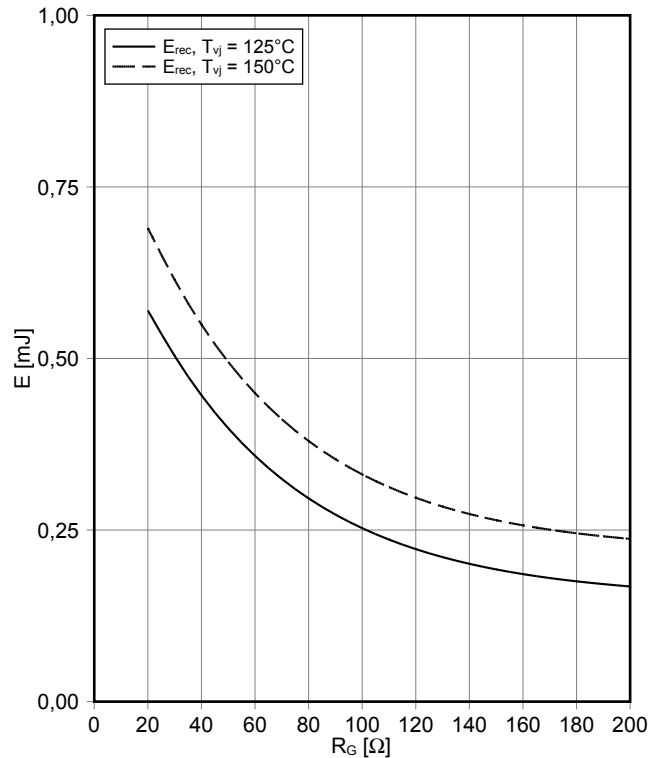
$$E_{rec} = f(I_F)$$

$R_{Gon} = 20 \Omega$, $V_{CE} = 300 \text{ V}$



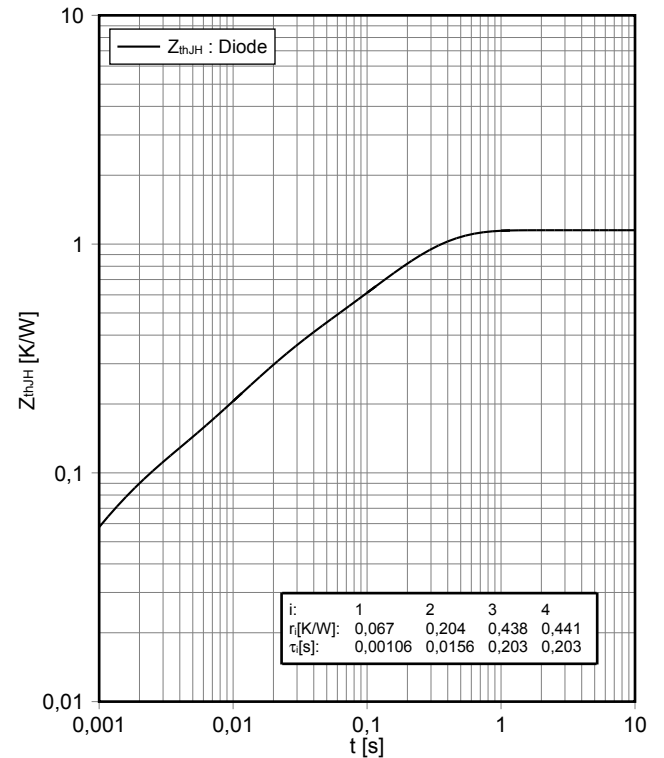
Schaltverluste Diode, D1 / D4 (typisch) switching losses Diode, D1 / D4 (typical)

$E_{rec} = f(R_G)$
 $I_F = 100\text{ A}$, $V_{CE} = 300\text{ V}$



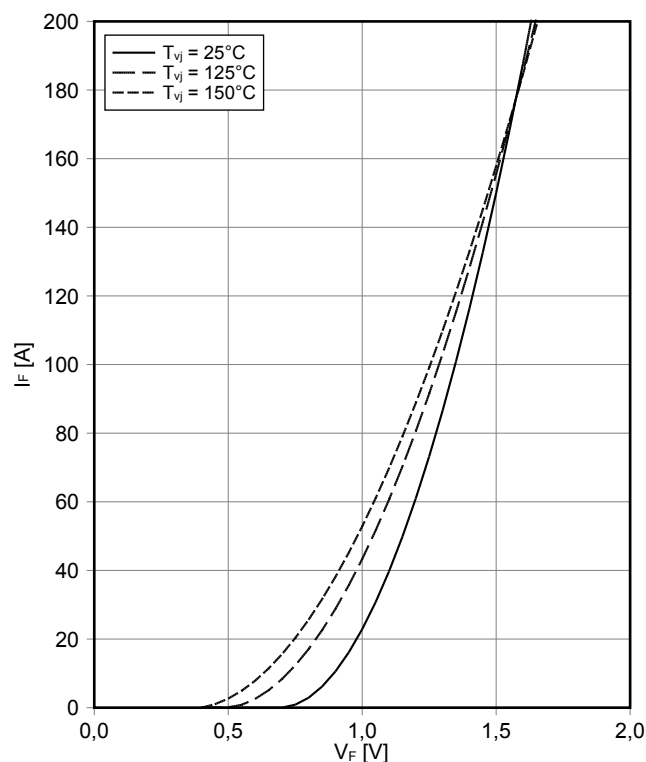
Transienter Wärmewiderstand Diode, D1 / D4 transient thermal impedance Diode, D1 / D4

$Z_{thJH} = f(t)$



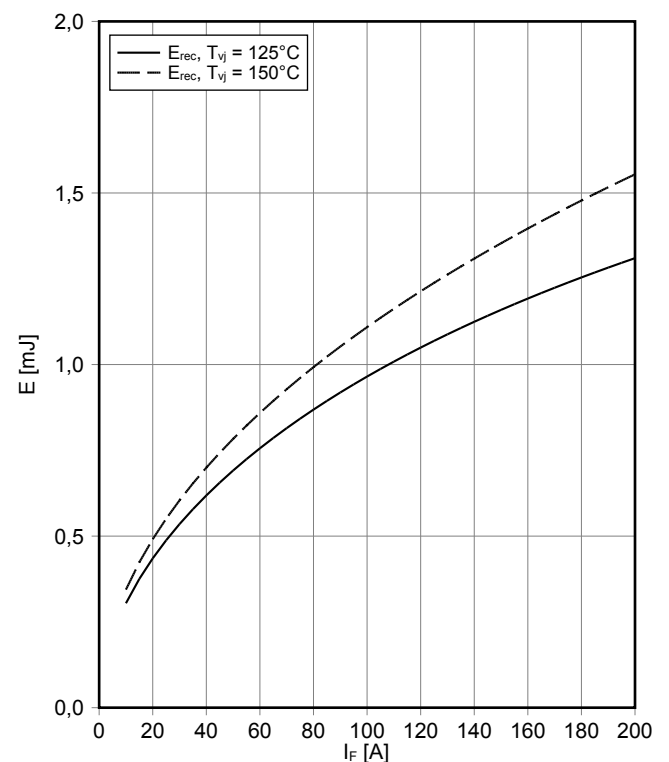
Durchlasskennlinie der Diode, D2 / D3 (typisch) forward characteristic of Diode, D2 / D3 (typical)

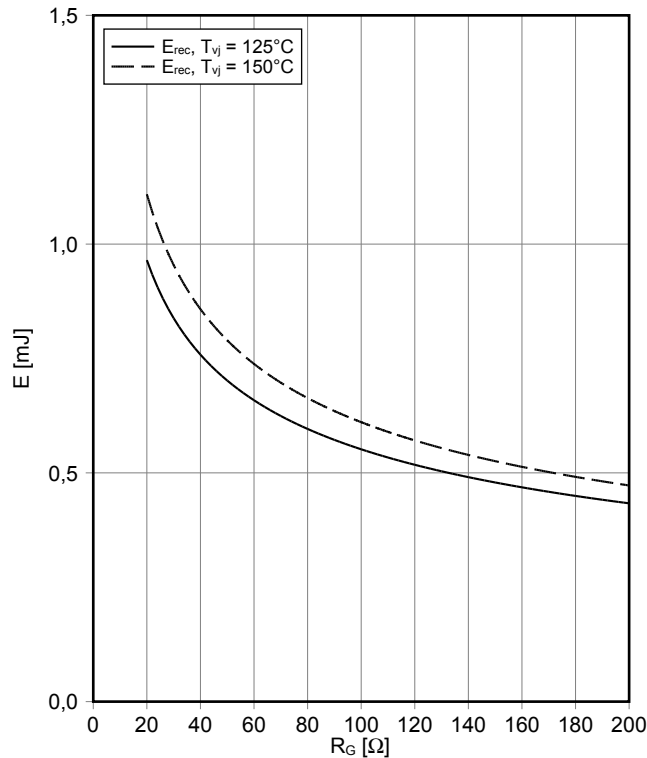
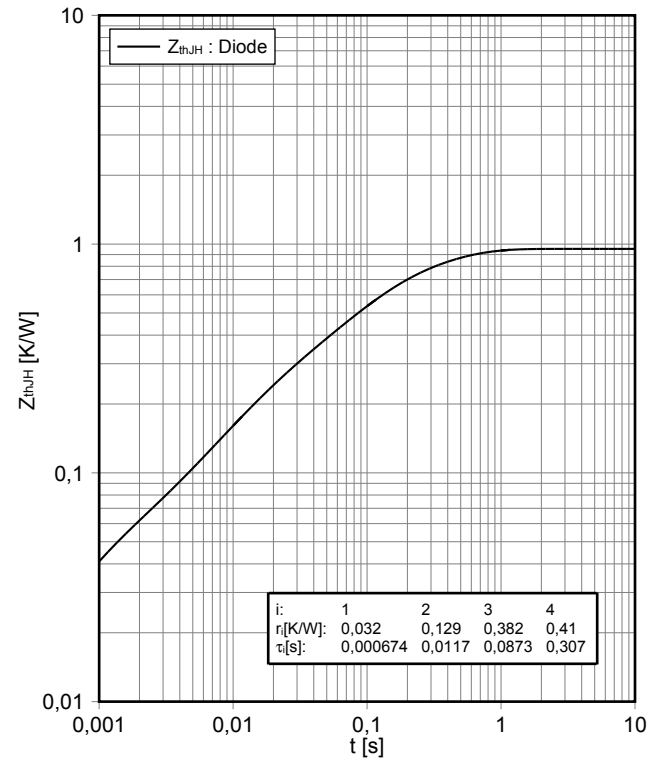
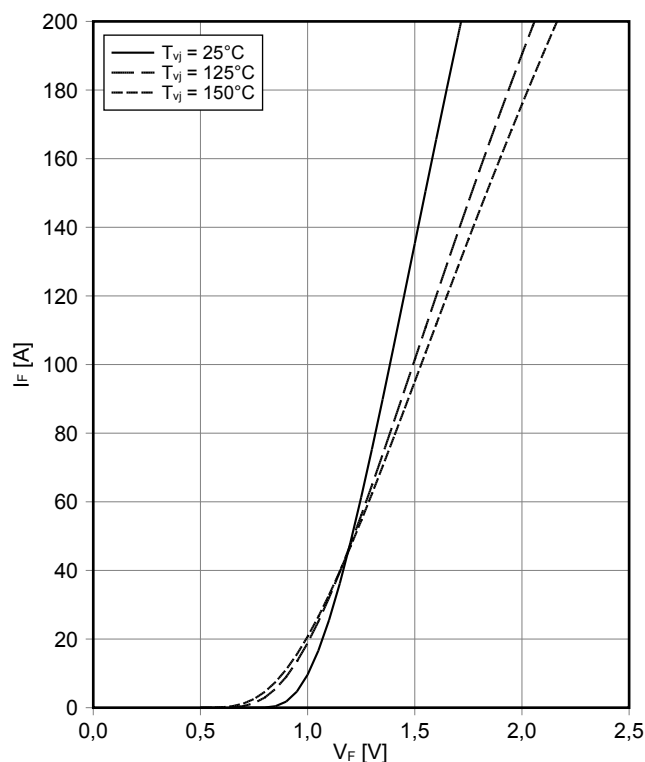
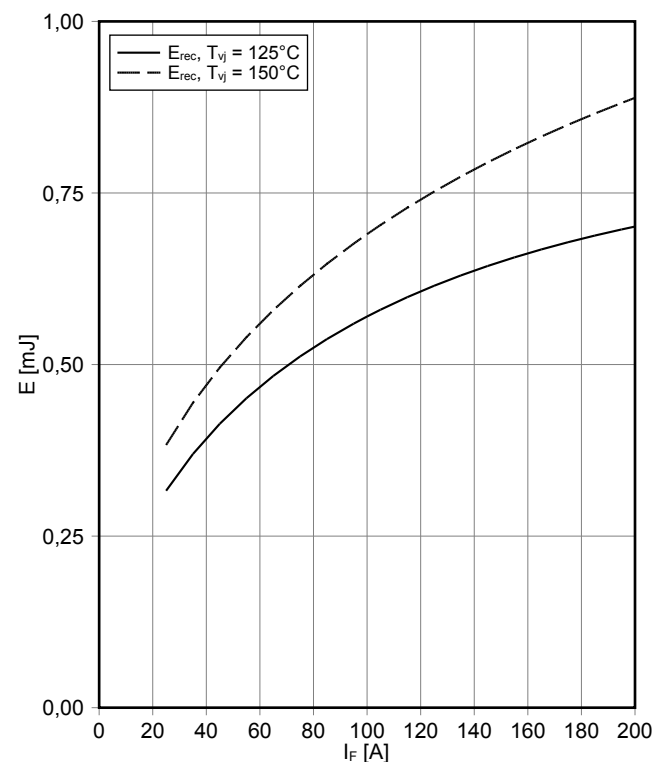
$I_F = f(V_F)$

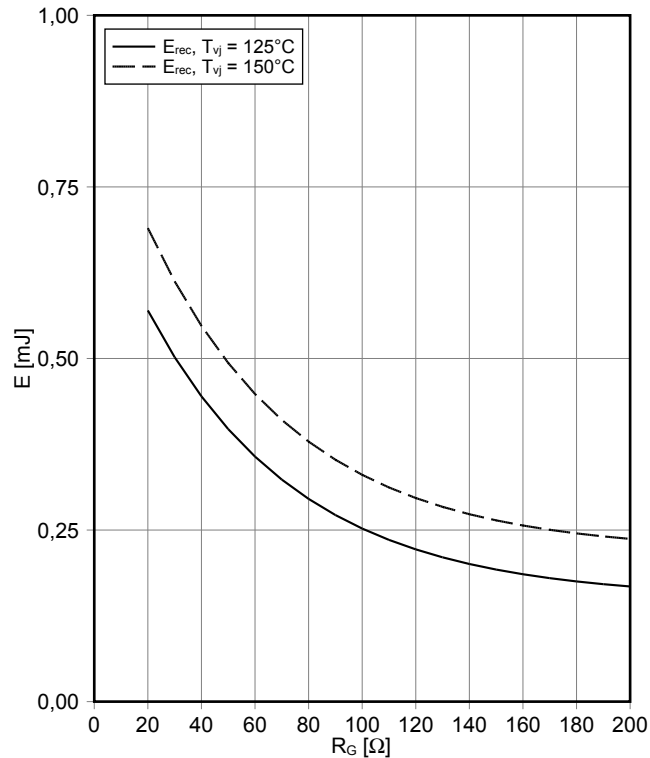
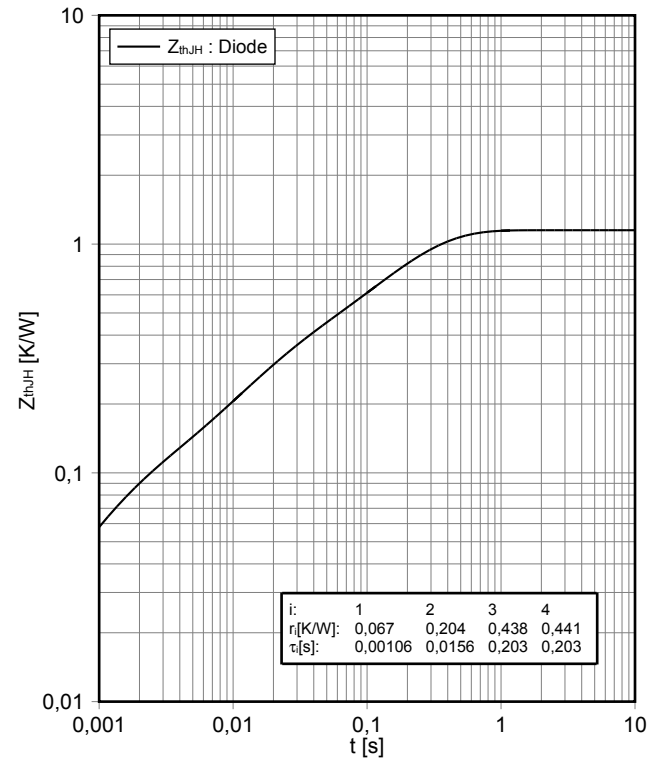
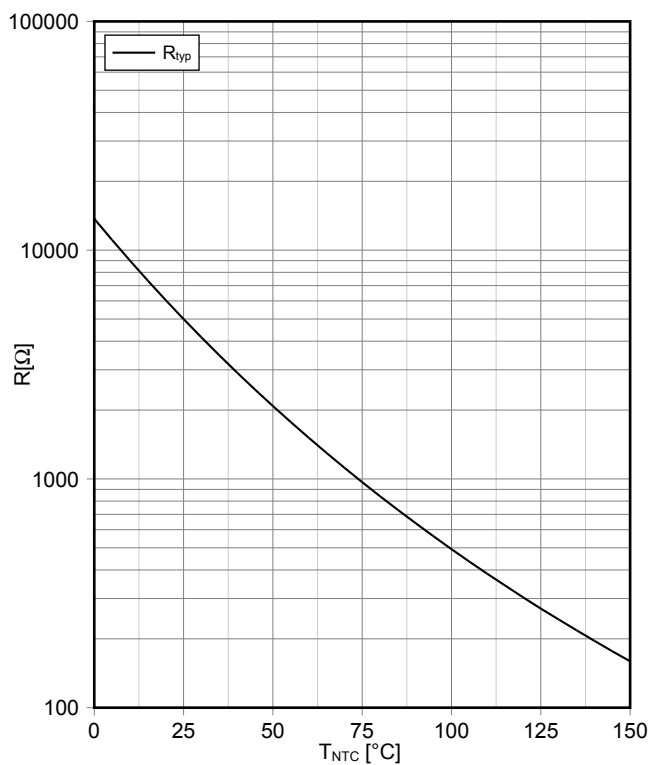


Schaltverluste Diode, D2 / D3 (typisch) switching losses Diode, D2 / D3 (typical)

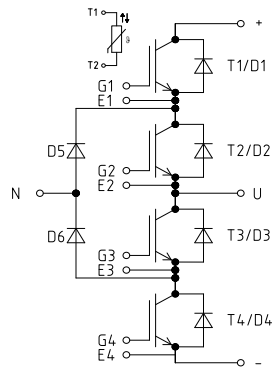
$E_{rec} = f(I_F)$
 $R_{Gon} = 20\ \Omega$, $V_{CE} = 300\text{ V}$



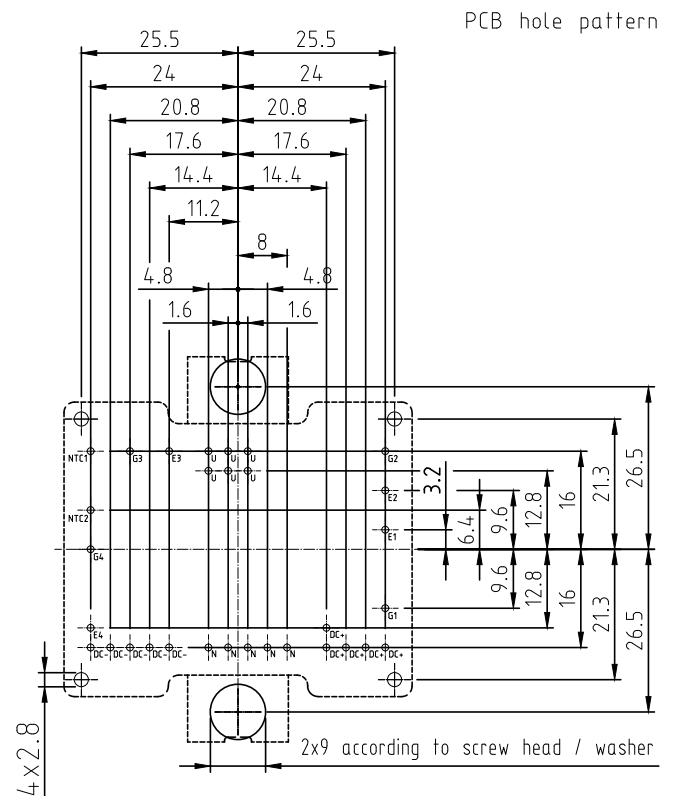
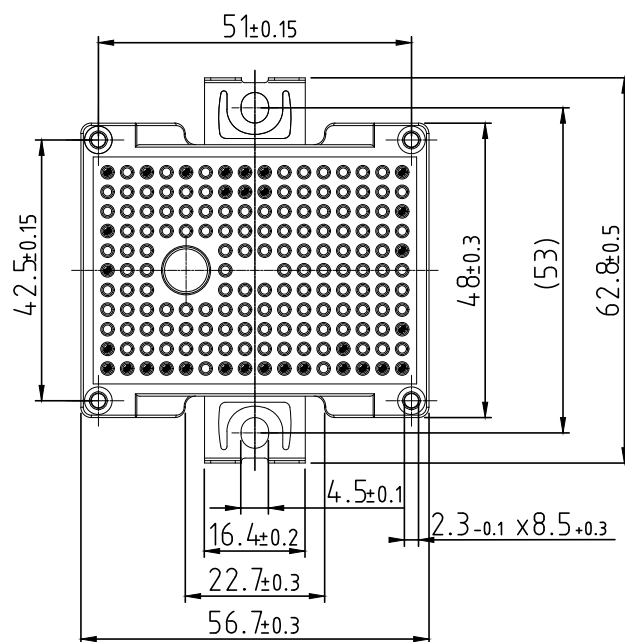
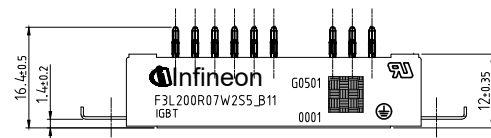
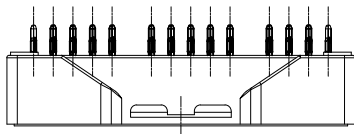
Schaltverluste Diode, D2 / D3 (typisch)
switching losses Diode, D2 / D3 (typical)
 $E_{rec} = f(R_G)$
 $I_F = 100\text{ A}$, $V_{CE} = 300\text{ V}$

Transienter Wärmewiderstand Diode, D2 / D3
transient thermal impedance Diode, D2 / D3
 $Z_{thJH} = f(t)$

Durchlasskennlinie der Diode, D5-D6 (typisch)
forward characteristic of Diode, D5-D6 (typical)
 $I_F = f(V_F)$

Schaltverluste Diode, D5-D6 (typisch)
switching losses Diode, D5-D6 (typical)
 $E_{rec} = f(I_F)$
 $R_{Gon} = 20\ \Omega$, $V_{CE} = 300\text{ V}$


Schaltverluste Diode, D5-D6 (typisch)
switching losses Diode, D5-D6 (typical)
 $E_{rec} = f(R_G)$
 $I_F = 100\text{ A}, V_{CE} = 300\text{ V}$

Transienter Wärmewiderstand Diode, D5-D6
transient thermal impedance Diode, D5-D6
 $Z_{thJH} = f(t)$

NTC-Widerstand-Temperaturkennlinie (typisch)
NTC-Thermistor-temperature characteristic (typical)
 $R = f(T_{NTC})$


Schaltplan / Circuit diagram



Gehäuseabmessungen / Package outlines



- Pin-Grid 3.2mm
- Tolerance of PCB hole pattern 
- Hole specification for contacts see AN 2009-01:
 Diameters of drill $\varnothing$ 1.15mm
 and copper thickness in hole 25-50 μ m

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